2SD1250, 2SD1250A

Silicon NPN triple diffusion planar type

For power amplification

For TV vartical deflection output

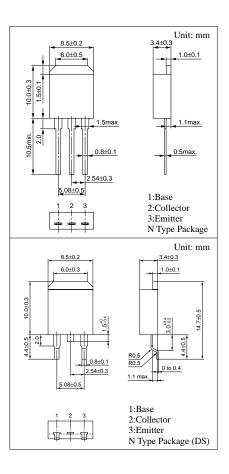
Complementary to 2SB0928 (2SB928) and 2SB0928A (2SB928A)

Features

- $\bullet~$ High forward current transfer ratio h_{FE} which has satisfactory linearity
- Low collector to emitter saturation voltage V_{CE(sat)}
- N type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment.

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Parameter		Symbol	Ratings	Unit	
Collector to	2SD1250	V	200	V	
base voltage	2SD1250A	V _{CBO}	200		
Collector to	2SD1250	N7	150	V	
emitter voltage	2SD1250A	V _{CEO}	180		
Emitter to base voltage		V _{EBO}	6	V	
Peak collector current		I _{CP}	3	А	
Collector current		I _C	2	А	
Collector power	T _C =25°C	D	30	W	
dissipation	Ta=25°C	P _C	1.3		
Junction temperature		Tj	150	°C	
Storage temperature		T _{stg}	-55 to +150	°C	

Absolute Maximum Ratings $(T_C=25^{\circ}C)$



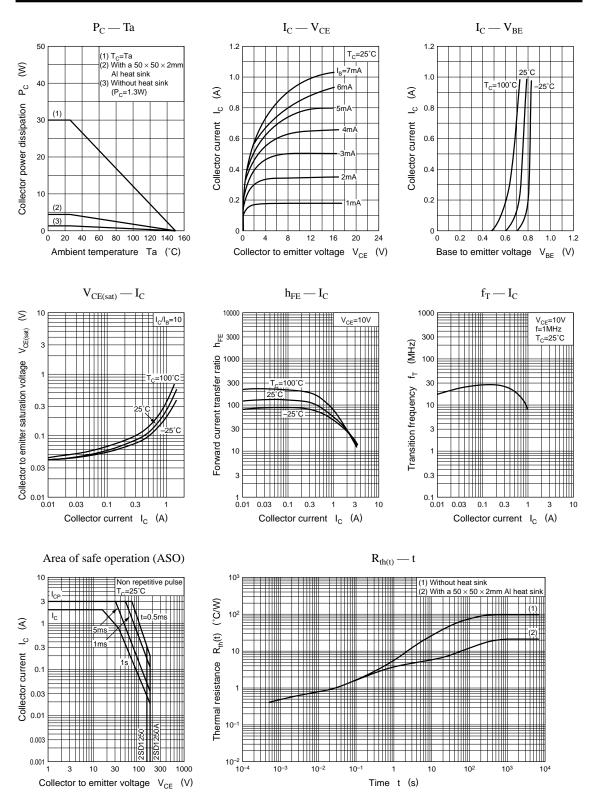
Electrical Characteristics $(T_c=25^{\circ}C)$

Paramete	er	Symbol	Conditions	min	typ	max	Unit
Collector cutoff curre	ent	I _{CBO}	$V_{CB} = 200V, I_E = 0$			50	μΑ
Emitter cutoff current		I _{EBO}	$V_{EB} = 4V, I_C = 0$			50	μΑ
Collector to base volt	tage	V _{CBO}	$I_{\rm C} = 500 \mu A, I_{\rm E} = 0$	200			V
Collector to emitter	2SD1250	V _{CEO}	$I_{\rm C} = 5 {\rm mA}, I_{\rm B} = 0$	150			- v
voltage	2SD1250A			180			
Emitter to base voltage		V _{EBO}	$I_{\rm E} = 500 \mu A, I_{\rm C} = 0$	6			V
Forward current transfer ratio		h _{FE1} *	$V_{CE} = 10V, I_C = 150mA$	60		240	
		h _{FE2}	$V_{CE} = 10V, I_{C} = 400mA$	50			
Base to emitter voltage		V _{BE}	$V_{CE} = 10V, I_{C} = 400mA$			1	V
Collector to emitter saturation voltage		V _{CE(sat)}	$I_{\rm C} = 500 {\rm mA}, I_{\rm B} = 50 {\rm mA}$			1	V
Transition frequency		f _T	$V_{CE} = 10V, I_C = 0.5A, f = 1MHz$		20		MHz

*hFE1 Rank classification

Rank	Q	Р
h _{FE1}	60 to 140	100 to 240

Note) The part numbers in the parenthesis show conventional part number.



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